ABSTRACT

Title: CIRCUIT MEMBER, MANUFACTURING METHOD FOR CIRCUIT MEMBERS, SEMICONDUCTOR DEVICE, AND SURFACE LAMINATION STRUCTURE FOR CIRCUIT MEMBER

A circuit member includes a frame substrate formed, by patterning a rolled copper plate or a rolled copper alloy plate, with a die pad portion for a semiconductor chip to be mounted thereon, and a lead portion for an electrical connection to the semiconductor chip, having rough surfaces formed as roughed surfaces on upsides and lateral wall sides of the die pad portion and the lead portion, and smooth surfaces formed on downsides of the die pad portion and the lead portion, and the die pad portion and the lead portion are buried in a sealing resin, having a downside of the lead portion exposed.

Fig. 9